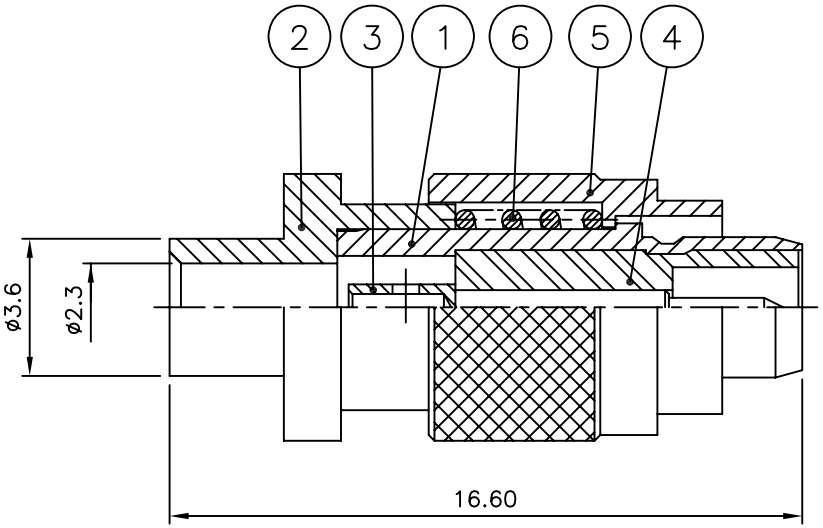
REVISION

REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	I.C.KIM	2012.06.29.
1	[설변처리No.201212-0002] 조립성 향상(BODY, CAP 치수 변경)	E.H.KIM	I.C.KIM	2012. 12. 06.
2	[설변처리No.201504-0002] 메이팅부 치수 표준화 적용	H.J.LEE	I.C.KIM	2015. 04. 07.



	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
	6	SPRING	1	SUS	부동태처리	DSR01102-5/1
1	5	CAP	1	MBsBD	Gold Plate	DCU02200-5/1 ~~DCU02192-5/2~~
	4	INSULATOR	1	TEFLON		DIN02021-N/1
	3	CONTACT	1	MBsBD	Gold Plate	DCT02613-5/1
1	2	BODY (B)	1	MBsBD	Gold Plate	DBD03089-5/1
2 1	1	BODY (A)	1	MBsBD	Gold Plate	DBD03088-5/4 ~~DBD03088-5/1~~

TOLERANCE	Decimal ±0.2	DATE	2015. 04. 07.
	Angle ±1°	APPROVED BY	I.C.KIM
		CHECKED BY	
MATERIAL		DRAWN BY	H.J.LEE
FINISH		SCALE 5/1	UNIT mm

KJ COMTECH
KJ COMTECH CO.,LTD.
RF & MICROWAVE TECHNOLOGY
Tel : 82-32-347-8015
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TITLE: SMBL50 CABLE PS 85

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